

# H&M7500

KÖNIG  
康尼格

## Desktop Low Pressure Molding Machine

低压注塑设备（桌上型）

适用于低压注塑热熔胶材料对电子元器件注塑封装保护，为敏感电子元器件，如：PCB/FPC，传感器，连接器，线束，电池等，提供更优的封装保护。

The machines are engineered for Low Pressure Injection Molding applications. Using hot-melt adhesive material to protect delicate electronic components, such as PCB/FPC, sensors, connectors, wiring harness, batteries, etc.



### 特点

- 注胶系统采用高可靠的齿轮泵和注胶枪，结构紧凑注胶精准稳定。
- 设备分段控温，胶缸、胶管和胶枪均可独立控制，温度控制精准。
- 注胶压力通过面板压力阀进行调节，操作简便。
- 胶缸、胶管、合模机构采用一体化设计，设备占地面积较小，可加入产线进行生产。
- 配有标准模具，适合中小型模具注胶，模具采用热流道控制，无水口料，节约成本。

### FEATURES

- Injection system using high reliability gear pump and glue guns, the injection is precise and stable with compact structure.
- The cylinder, hose and gun can be controlled independently, and the temperature control is accurate.
- Injecting pressure is easy to adjust through the control panel.
- Melting Tank, hose and cylinder clamping mechanism use all-in-one design, small space needed, can be place in the production line.
- Use standard mold, suitable for small mold injection, and equipped with hot runner, no material waste.

左右移模 | 一个上模搭配两个下模 | 稳定高效  
桌上型一体式，占地面积小，适合中小型模具注胶

One upper mold for two lower mold with left-right transfer mode, stable and efficient. Desk type all-in-one, less space occupation, suitable for small size mold



### 低压注塑工艺 Low Pressure Injection Molding



150~200°C  
极低的注塑温度



1.5~60bar  
极低的注塑压力



1S  
成型速度快至1s



IP67  
防水防尘

以上数据取决于具体产品，可能存在变化  
Characters depend on project.

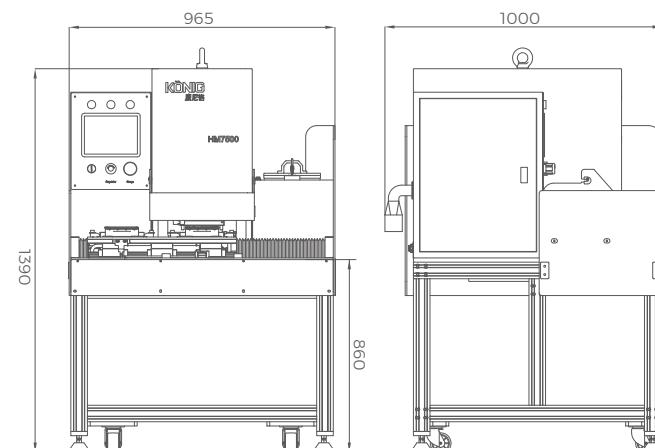
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Left-right transfer mode  
Suitable for small size mold  
左右移模 | 适合中小型模具注胶

熔胶系统与数量	
Melting Tank Model&Q'ty	KH02(2 Liter)×1PC
注胶管型号与数量	
Heated Hose Model&Q'ty	KJ10×1PC
输入电压	220VAC/1Phase/50 or 60Hz
Electricity	
用气量	
Air Consumption	0.1 m <sup>3</sup> /min
温控分区	
Temperature Control Zones	3
最高设定温度	
Max. Setting Temperature	up to 250°C
最大功率	
Max. Power	3.0Kw
最低工作气压	
Min. Air Pressure	0.5Mpa
合模方式	
Clamping Device	气缸(Cylinder)
合模压力	
Clamping Force	Max.1.2Ton
合模行程	
Clamping Stroke (mm)	125mm
标准模具尺寸	
Standard Mold Size(mm)	180×160×130
控制系统	
Control System	PLC+7" HMI
工作台高度	
Work Station Height(mm)	860
机台尺寸重量	
Machine Size(mm)	965×1000×1390 (430Kgs)
包装尺寸重量	
Packing Size(mm)	1265×1205×1670 (470Kgs)

高生产效率	High Efficiency	
低温低压，成型快速，无损敏感电子元器件	Perfect protect sensitive electronic components with low temperature & low pressure	
高产品良率	High Yield	
模具成型，高一致性，培训简单操作便捷	High consistency with mold forming, easy to operate	
节约材料	Save Material	
无需灌封外壳，无需多次操作，一次快速成型	No need plastic shell, no need to operate many times	
和谐生产环境	ECO Friendly	
生产过程中无有毒烟气产生，无化学反应	No toxic smoke during production process	



可选配设备	<input type="checkbox"/> 材料干燥机	<input type="checkbox"/> 冷水机	<input type="checkbox"/> 上下料机械手	<input type="checkbox"/> 自动加料系统
Optional Equipment	Material dryer	Water chillers	Loading manipulators	Automatic feeding system

